



(总公司) 上海大族富创得科技股份有限公司
(HEAD OFFICE) SHANGHAI FORTREND TECHNOLOGY CO.,LTD

半导体真空传输系统

SEMICONDUCTOR VACUUM TRANSFER SYSTEM

无锡富创得精密设备有限公司 WUXI FORTREND PRECISION EQUIPMENT CO.,LTD

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微信公众号



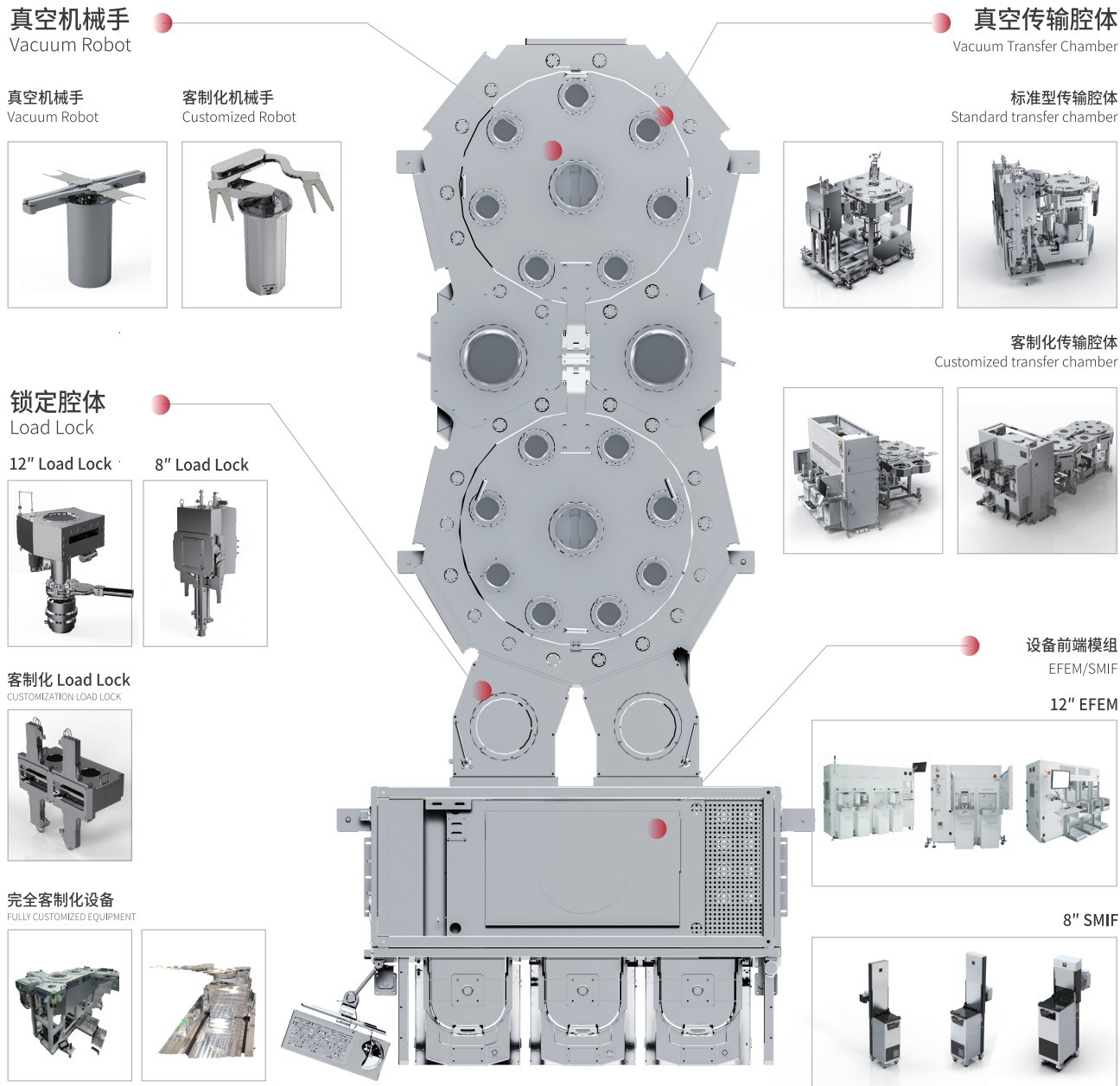
官方网站

经销商 Distributors

英国 UK
Sistem Technology
Address: Grafton Suite, Caswell Science & Technology Park, Towcester, Northants, NN12 8EQ, UK
Tel: (44) 1327 317621

韩国 South Korea
SD Solution
Address: #509,Biz-tower,63-12,Dongtancheomdansaneop 1-ro,Hwaseong-si,Gyeonggi-do,Republic of korea
Tel: (81) 42-468-4164

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The product pictures shown in this volume are rendered or taken. The technical parameters and pictures may be different from the actual products due to improvement and upgrade, etc., for reference only. Please confirm with your account manager for details.



- 设备前端可选配EFEM / SMIF, EFEM可提供标准型与客制型

EFEM / SMIF can be optionally equipped at the equipment front end, with EFEM offering standard and custom types.
- Load Lock可选不同结构与传输方式

Load Lock can be chosen with different structures and transfer methods.
- 可根据实际工艺腔要求制作客制化传输腔体

Customized transfer chambers can be made according to actual process chamber requirements.

- 真空机械手可根椐实际工况选择不同型号与末端执行器

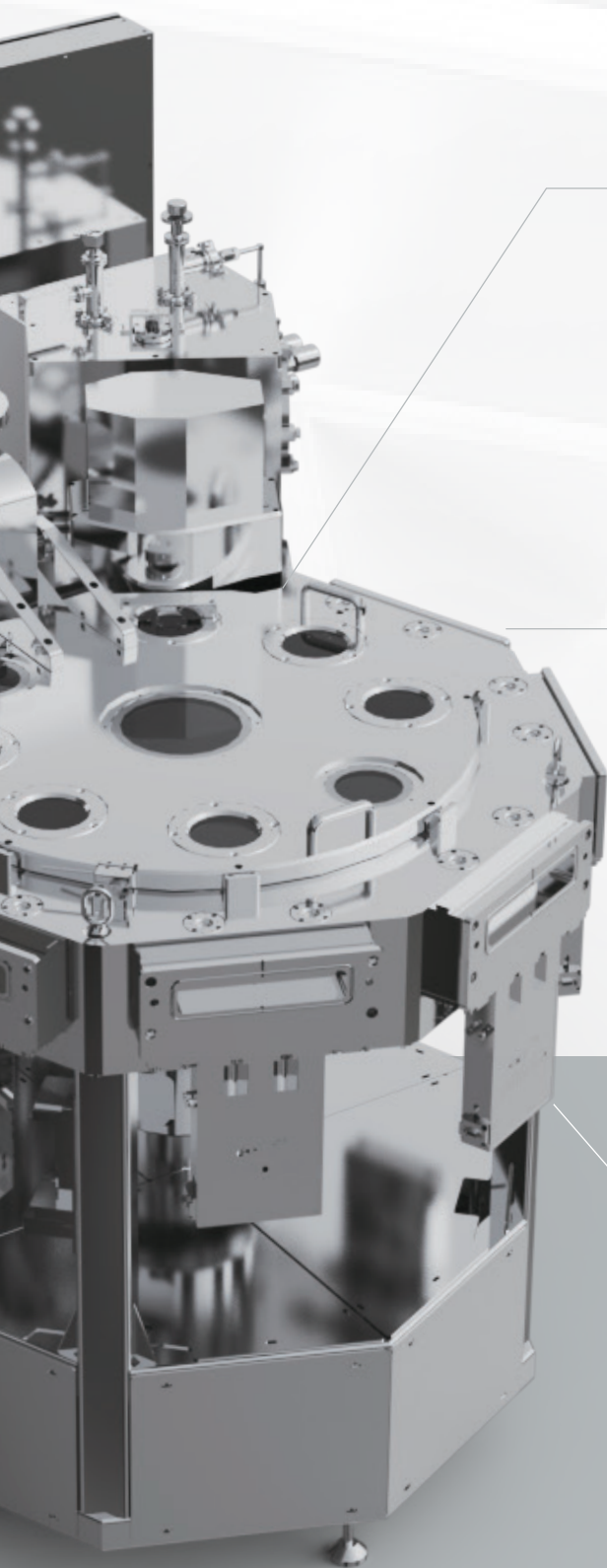
Vacuum mechanical arms can be selected with different models and end effectors according to actual operating conditions.
- 传输腔体与Load Lock可选内置的定向 / 冷却/ 预热模组

Transfer chambers & Load Lock can include optional built-in directional / cooling / pre-heating modules.
- 可选配的AWC功能、Buffer 功能、晶圆存储模组

Optional features include AWC functionality, Buffer functionality, wafer storage modules.

客户信息 CUSTOM INFO.			
公司名称 Company name		地址 Company Add.	
对接人 Contact person		职务 Postition	
电话 Phone number		邮箱 E-mali	

客户需求配置表 CUSTOM REQUIREMENTS CONFIG.			
工艺设备类型 Process equipment type	☐ PVD ☐ CVD ☐ ALD ☐ EBL ☐ 刻蚀 Etch ☐ 其他 Other _____		
晶圆&载具规格 Wafer & Carrier Spec.	晶圆尺寸 Wafer Size	☐ 150mm (6 ") ☐ 200mm (8 ") ☐ 300mm (12 ") ☐ 其他 Other _____mm	
	晶圆类型 Wafer Type	☐ 普通 Normal _____μm ☐ TAIKO _____μm ☐ 其他 Other _____ 厚度 Thickness _____μm	
	晶圆材质 Wafer Material	☐ 单晶硅 Si ☐ 碳化硅 SiC ☐ 玻璃 Glass ☐ 其他 Other _____μm	
	载具类型 Carrier Type	☐ FOUP/FOSB (SEMI) ☐ SMIF POD ☐ Open Cassette ☐ 其他 Other _____	
	载具规格 Carrier Spec.	生产商 Maker_____ 型号 Model _____	
	载具供应方法 Carrier Feeding	☐ 人工 Operator ☐ AGV ☐ OHT ☐ 其他 Other _____	
传输模组规格 Transfer Moudle Spec.	主设备 Primary Equipment	洁净度 Cleanness	☐ ISO - Class 3 ☐ 其他 Other _____
		对接工艺腔数量 Docking PM Qty.	☐ 1 ☐ 3 ☐ 4 ☐ 其他 Other _____
		对接Load Lock数量 Docking Load Lock Qty.	☐ 1 ☐ 2 ☐ 其他 Other _____
	前端设备 Front-end Equipment	☐ EFEM ☐ SMIF ☐ 不选配 None-opention ☐ 其他 Other _____	
备注事项 Note	请在您的客户经理协助下填写此表格 Please fill out this form with the assistance of your account manager.		



 **核心组件自主研发生产,软硬件垂直整合**
Independent research and development and production of core hardware and software.

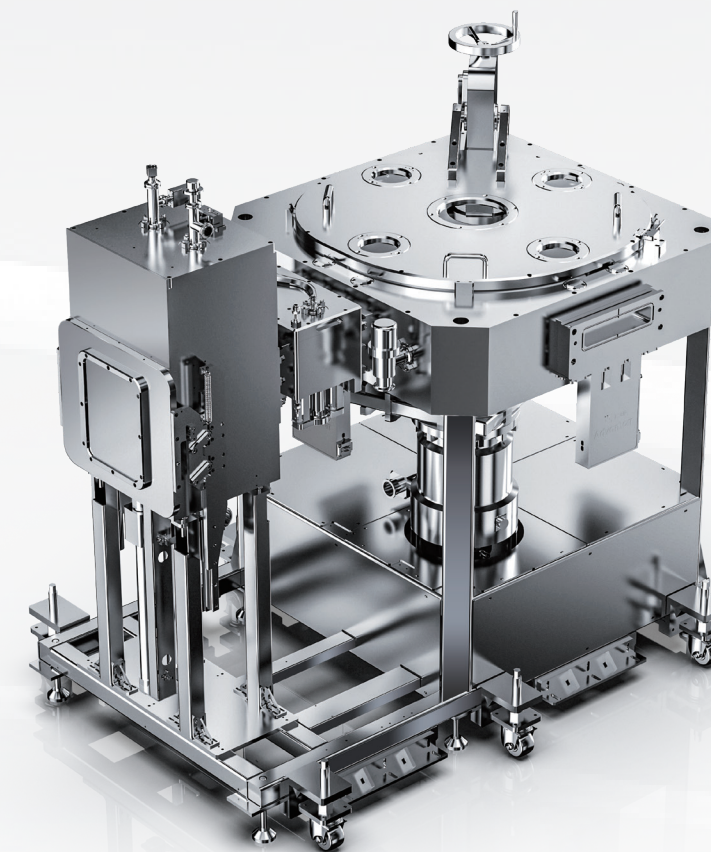
真空传输系统核心组件均由富创得自主设计研发,并在自有生产基地组装生产,实现更好的交期与性能。
The core components of the vacuum transfer system are independently designed and developed by Fortrend, and assembled and produced at its own production base, achieving better delivery times and performance.

 **深耕半导体领域多年,适配多数前道工艺设备**
Deeply rooted in the semiconductor field for many years, adaptable to most semiconductor front-end process equipment.

富创得深耕半导体传输领域四十余年,设备适配半导体前道工艺多数制程。所有量产设备均符合SEMI标准,适配各种晶圆/掩膜等半导体/泛半导体物料工艺设备的工况需求。
Fortrend has been deeply involved in the semiconductor transport field for over forty years, with equipment adapted to most semiconductor front-end processes. All production equipment complies with SEMI standards and adapts to the process requirements of various semiconductor/microelectronic material processing equipment, such as wafers/masks.

 **提供标准化模块与客制化方案,满足不同需求**
Providing standardized modules and customized solutions to meet different requirements.

真空传输系统可提供标准方案供制程设备进行对接,也可根据客户要求进行设备的客制化,软硬件均有成熟方案可供选择,满足不同的制程设备与实际工况的需求。
Fortrend vacuum transfer systems can provide standard solutions for process equipment integration and can also be customized according to customer requirements. Both software and hardware have mature solutions to choose from, meeting the needs of different process equipment and actual operating conditions.

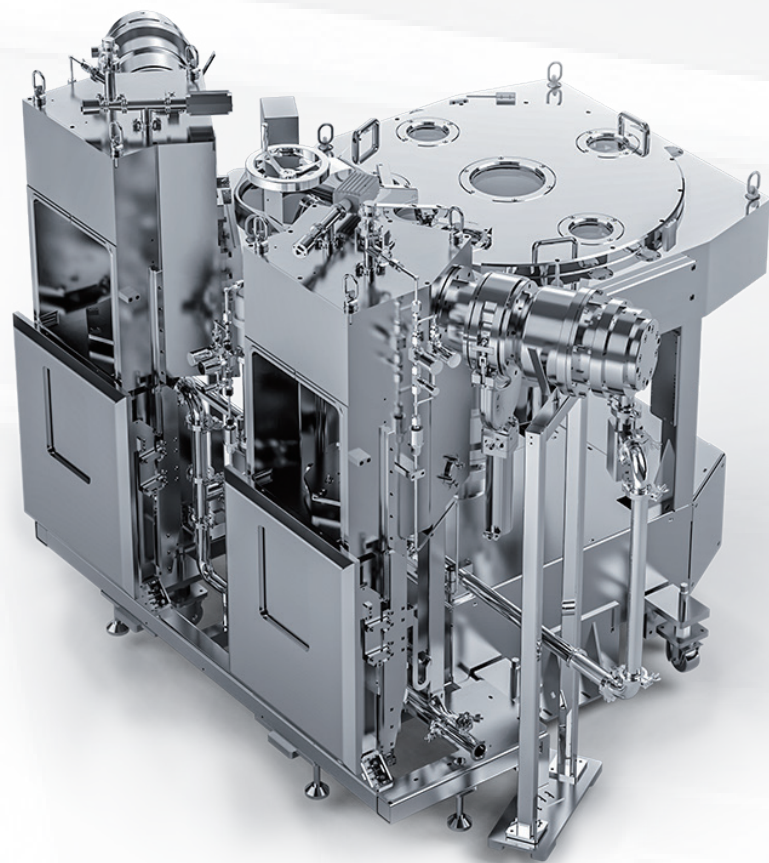


四边形晶圆真空传输平台 Quadrilateral Wafer Vacuum Transfer Platform

 **适用于 SUITABLE FOR**

- 150mm,200mm晶圆(含TAIKO、Frame晶圆)、掩膜、泛半导体物料(光伏硅板等)
Wafers up to 200mm (including TAIKO, Frame wafers), masks, and general semiconductor materials (such as photovoltaic silicon wafers, etc.)
- PVD、CVD、ALD等半导体前道/泛半导体工艺设备。
PVD, CVD, ALD, and other semiconductor front-end / general semiconductor process equipment.
- 高洁净度传输,晶圆传输洁净度Class1;
High cleanliness transmission, wafer surface cleanliness Class 1.
- 高效率,高稳定性传输,传输效率 ≥ 200 pcs/h; Up time: $\geq 98\%$;
Efficient and stable transmission, with a transmission efficiency of ≥ 200 pcs/h; Up time: $\geq 98\%$;
- 支持国产化替代,客户化定制。
Support localization substitution and customized customization.

 五边形标准形真空传输系统
PENTAGONAL STANDARD VACUUM TRANSFER SYSTEM

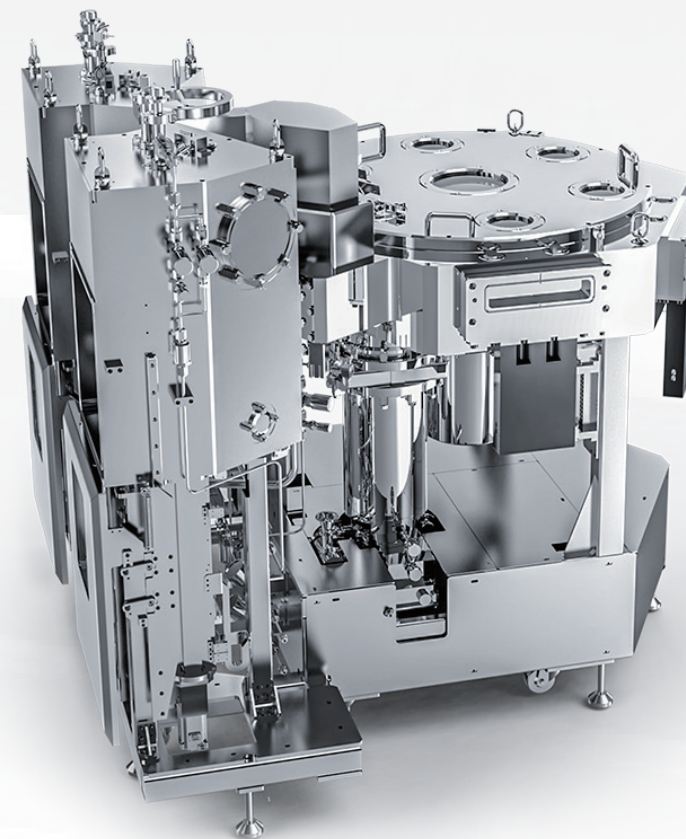


五边形晶圆真空传输平台
PENTAGON WAFER VACUUM TRANSFER PLATFORM

 适用于 SUITABLE FOR

- 150mm,200mm晶圆(含TAIKO、Frame晶圆)、掩膜、泛半导体物料(光伏硅板等)
Wafers up to 200mm (including TAIKO, Frame wafers), masks, and general semiconductor materials (such as photovoltaic silicon wafers, etc.)
- PVD、CVD、ALD等半导体前道/泛半导体工艺设备
PVD, CVD, ALD, and other semiconductor front-end / general semiconductor process equipment.
- 高洁净度传输, 晶圆传输洁净度Class1;
High cleanliness transmission, wafer surface cleanliness Class 1.
- 高效率, 高稳定性传输, 传输效率 ≥ 200 pcs/h; Up time: $\geq 98\%$;
Efficient and stable transmission, with a transmission efficiency of ≥ 200 pcs/h; Up time: $\geq 98\%$;
- 支持国产化替代, 客户化定制。
Support localization substitution and customized customization.

 六边形标准形真空传输系统
HEXAGONAL STANDARD VACUUM TRANSFER SYSTEM



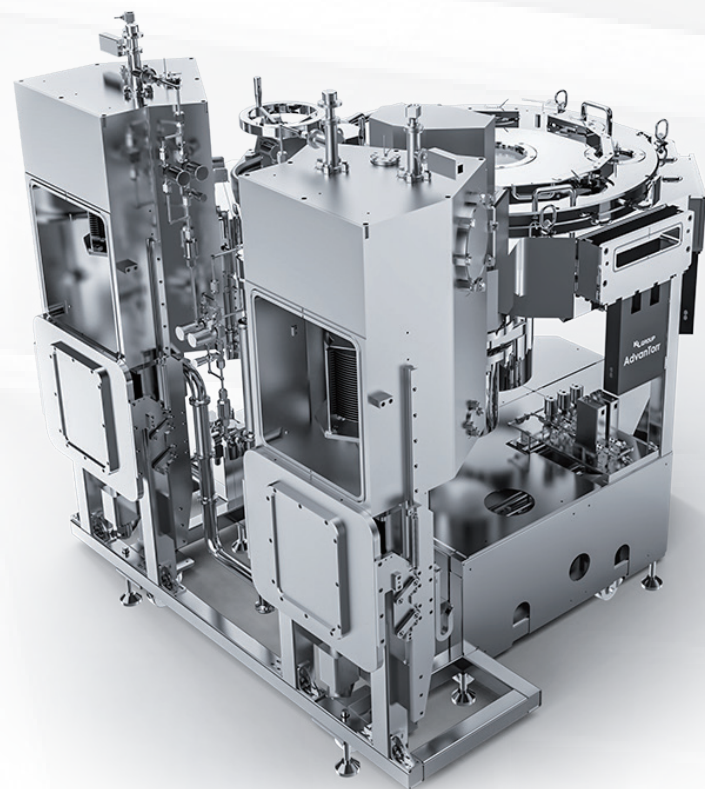
六边形晶圆真空传输平台
HEXAGON WAFER VACUUM TRANSFER PLATFORM

 适用于 SUITABLE FOR

- 150mm,200mm晶圆(含TAIKO、Frame晶圆)、掩膜、泛半导体物料(光伏硅板等)
Wafers up to 200mm (including TAIKO, Frame wafers), masks, and general semiconductor materials (such as photovoltaic silicon wafers, etc.).
- PVD、CVD、ALD等半导体前道/泛半导体工艺设备。
PVD, CVD, ALD, and other semiconductor front-end / general semiconductor process equipment.
- 高洁净度传输, 晶圆传输洁净度Class1;
High cleanliness transmission, wafer surface cleanliness Class 1.
- 高效率, 高稳定性传输, 传输效率 ≥ 200 pcs/h; Up time: $\geq 98\%$;
Efficient and stable transmission, with a transmission efficiency of ≥ 200 pcs/h; Up time: $\geq 98\%$;
- 支持国产化替代, 客户化定制。
Support localization substitution and customized customization.

七边形标准形真空传输系统

HEPTAGON STANDARD VACUUM TRANSFER SYSTEM



七边形晶圆真空传输平台

HEPTAGON WAFER VACUUM TRANSFER PLATFORM

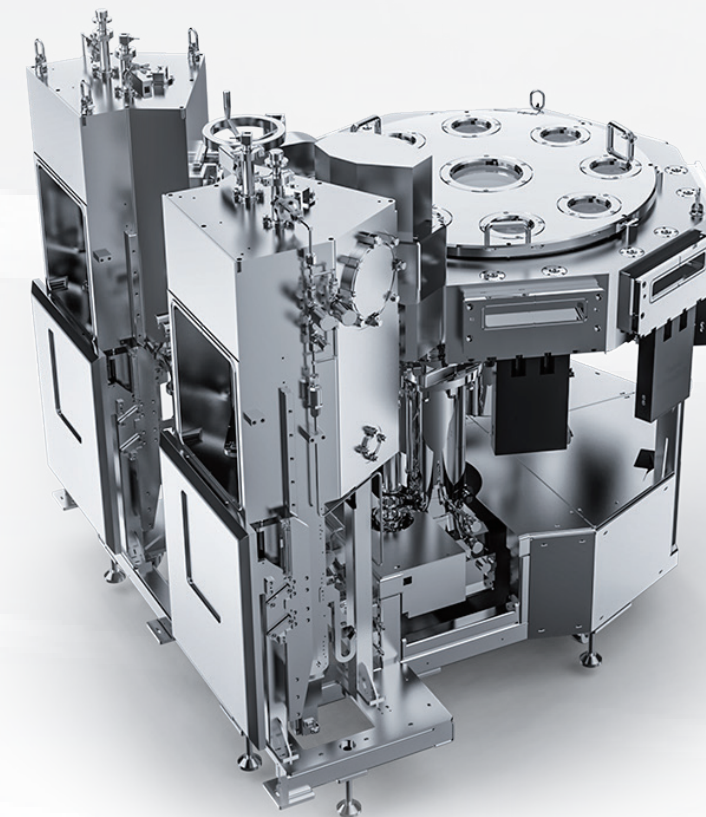


适用于 SUITABLE FOR

- 150mm,200mm晶圆(含TAIKO、Frame晶圆)、掩膜、泛半导体物料(光伏硅板等)
Wafers up to 200mm (including TAIKO, Frame wafers), masks, and general semiconductor materials (such as photovoltaic silicon wafers, etc.).
- PVD、CVD、ALD等半导体前道/泛半导体工艺设备。
PVD, CVD, ALD, and other semiconductor front-end / general semiconductor process equipment.
- 高洁净度传输, 晶圆传输洁净度Class1;
High cleanliness transmission, wafer surface cleanliness Class 1.
- 高效率, 高稳定性传输, 传输效率 ≥ 200 pcs/h; Up time: $\geq 98\%$;
Efficient and stable transmission, with a transmission efficiency of ≥ 200 pcs/h; Up time: $\geq 98\%$;
- 支持国产化替代, 客户化定制。
Support localization substitution and customized customization.

八边形标准形真空传输系统

OCTAGON STANDARD VACUUM TRANSFER SYSTEM



八边形晶圆真空传输平台

OCTAGON WAFER VACUUM TRANSFER PLATFORM

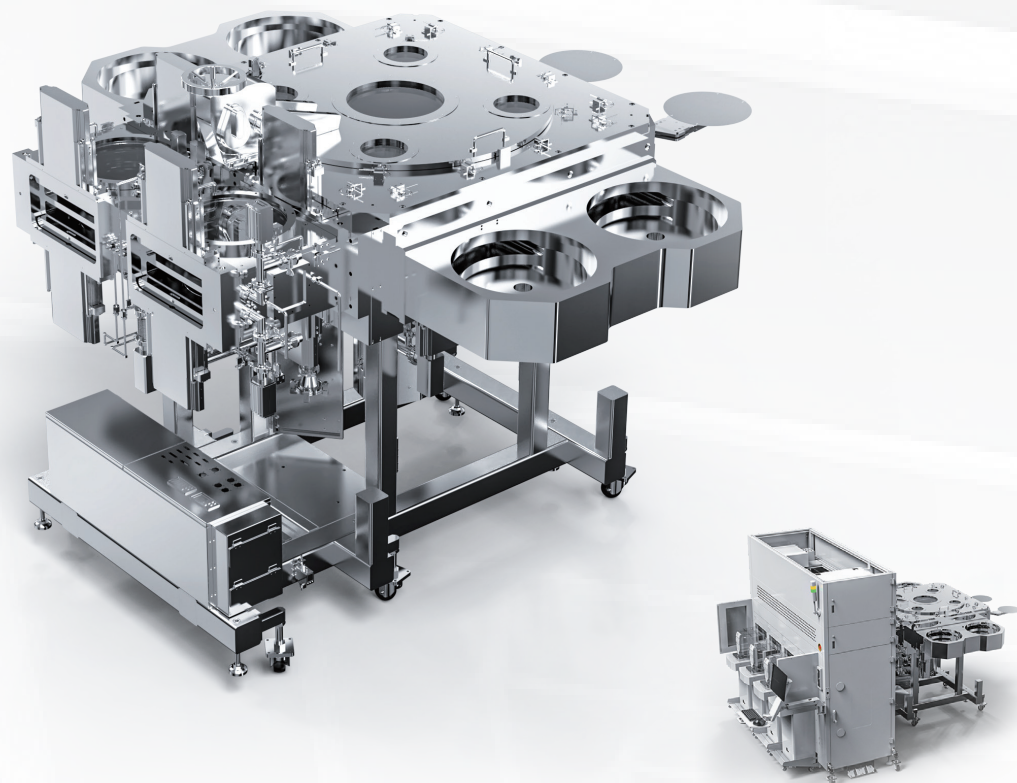


适用于 SUITABLE FOR

- 150mm,200mm晶圆(含TAIKO、Frame晶圆)、掩膜、泛半导体物料(光伏硅板等)
Wafers up to 200mm (including TAIKO, Frame wafers), masks, and general semiconductor materials (such as photovoltaic silicon wafers, etc.).
- PVD、CVD、ALD等半导体前道/泛半导体工艺设备。
PVD, CVD, ALD, and other semiconductor front-end / general semiconductor process equipment.
- 高洁净度传输, 晶圆传输洁净度Class1;
High cleanliness transmission, wafer surface cleanliness Class 1.
- 高效率, 高稳定性传输, 传输效率 ≥ 200 pcs/h; Up time: $\geq 98\%$;
Efficient and stable transmission, with a transmission efficiency of ≥ 200 pcs/h; Up time: $\geq 98\%$;
- 支持国产化替代, 客户化定制。
Support localization substitution and customized customization.

12寸双入料VTM

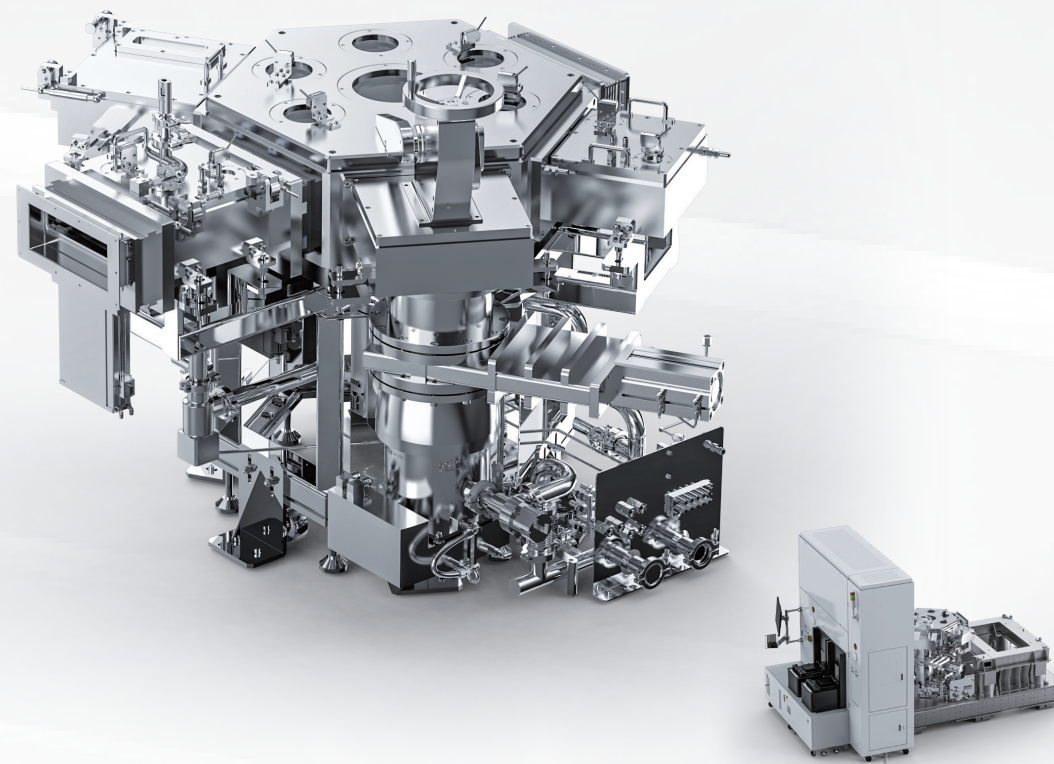
12-INCH DUAL-FEED VTM + EFEM



客制化—12寸双入料VTM

MASK真空传输平台

MASK VACUUM TRANSFER PLATFORM



客制化—MASK真空传输平台

晶圆双入料真空传输平台

DUAL-FEED WAFER VACUUM TRANSFER PLATFORM



适用于 SUITABLE FOR

■ 300mm晶圆(含TAIKO、Frame晶圆)、掩膜、泛半导体物料(光伏硅板等)

Wafers up to 300mm (including TAIKO, Frame wafers), masks, and general semiconductor materials (such as photovoltaic silicon wafers, etc.).

■ PVD、CVD、ALD等半导体前道/泛半导体工艺设备。

PVD, CVD, ALD, and other semiconductor front-end / general semiconductor process equipment.

■ 高洁净度传输, 晶圆传输洁净度Class1;

High cleanliness transmission, wafer surface cleanliness Class 1.

■ 高效率, 高稳定性传输, 传输效率 ≥ 200 pcs/h; Up time: $\geq 98\%$;

Efficient and stable transmission, with a transmission efficiency of ≥ 200 pcs/h; Up time: $\geq 98\%$;

■ 支持国产化替代, 客户化定制。

Support localization substitution and customized customization.

MASK真空传输平台

MASK Vacuum Transfer Platform



适用于 SUITABLE FOR

■ 全尺寸掩膜、泛半导体物料(光伏硅板等):

Full-size masks, pan-semiconductor materials (photovoltaic silicon panels, etc.).

■ 曝光、光刻等半导体前道/泛半导体工艺设备。

Exposure, photolithography and other semiconductor front-channel/pan-semiconductor process equipment.

■ 高洁净度传输, 晶圆传输净度Class1;

High cleanliness transmission, wafer surface cleanliness Class 1

■ 高效率, 高稳定性传输, 传输效率 ≥ 200 pcs/h; Up time: $\geq 98\%$;

Efficient and stable transmission, with a transmission efficiency of ≥ 200 pcs/h; Up time: $\geq 98\%$;

■ 支持国产化替代, 客户化定制。

Support localization substitution and customized customization.